



MS ISSUE FEE
PATENT
0763-0173P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Dong K. SOHN et al. Conf.: 9674
Appl. No.: 10/620,608 Group: 2814
Filed: July 17, 2003 Examiner: Long PHAM
For: METHOD OF FORMING FILM FOR REDUCED OHMIC
CONTACT RESISTANCE AND TERNARY PHASE LAYER
AMORPHOUS DIFFUSION BARRIER

AMENDMENT UNDER 37 C.F.R. § 1.312

MS ISSUE FEE
Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

November 17, 2004

Sir:

Further to the Notice of Allowance mailed November 15, 2004,
the following amendments and remarks are respectfully submitted in
connection with the above-identified application.

This amendment includes amendments to the specification,
claims and remarks.

*Enter amendments in part
to spec only
LP (2/19/05)*